

Appl. No. 10/085,725
Reply to Office action of 01/20/2004

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A batch cleaning method for removing particles on a plurality of semiconductor wafers, comprising the step of performing a first cleaning process in which said semiconductor wafers are cleaned for a prescribed time by immersing them in a first cleaning solution comprising ultra-pure water containing a prescribed gas in a range 20% to 50% of the saturated concentration in a first cleaning tank, and in which ultrasonic waves are supplied to said first cleaning solution in said first process.
2. (original) A method for removing particles on semiconductor wafers as described in claim 1 in which said prescribed gas is hydrogen.
3. (original) A method for removing particles on semiconductor wafers as described in claim 2 in which the in-solution concentration of the hydrogen in said first cleaning solution is in the range 0.3 ppm to 0.8 ppm.
4. (original) A method for removing particles on semiconductor wafers as described in claim 2 in which said first cleaning solution contains ammonia in an in-solution concentration in the range 1 ppm to 10 ppm.
5. (original) A method for removing particles on semiconductor wafers as described in claim 2, further comprising the step of, before said first cleaning process, performing a second cleaning process in which the semiconductor wafers are cleaned for a prescribed time by immersing them in a second cleaning solution consisting of ultra-pure water containing a prescribed quantity of ozone in a second cleaning tank.
6. (currently amended) A method for removing particles on semiconductor wafers as described in claim 5 further comprising the step of, after said second cleaning process, performing a third cleaning process in which said semiconductor wafers are cleaned for a prescribed time by immersing them in a third cleaning solution ~~consisting of~~ comprising an HF mixed solution in a third cleaning tank.
7. (cancelled).